



How to test bonds » external sources » general

- ASTM International Standards
- Deutsches Institut für Normung
- Delphion Research intellectual property network
- Defense Supply Center Columbus - Mil Specs & Drawings
- International Organisation for Standardization
- Joint Equipment and Materials Initiative
- National Institute of Standards and Technology
- National Resource for Global Standards
- Physikalisch Technischen Bundesanstalt
- MIL-STD-883

How to test bonds?

- Cold Bump Pull (CBP)
- Tweezer Pull (WP)
- Wire Pull (WP)

External sources

- General
- Semiconductor alliances
- Semiconductor engineering
- Process control
- Articles and papers

This information can also be found at www.qualitycontrol.how

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Other offices

- Germany
- Taiwan
- Thailand
- United Kingdom
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Bond testers

- Condor *Sigma*
- Condor *Sigma Lite*
- Condor *Sigma W12*
- Condor *150HF*

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